



Ref. under 37 CFR 1.116
--Expedited Procedure--
Technology Center 2800

AF/2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#7/B(12)

In re the Application of:

Baldonado, et al.

Docket No.: TI-32857

Serial No.: 10/066,421

Examiner: Clark, S. V.

5/13/03

Filed: 01/30/02

Art Unit: 2815

For: Method and System of Wire Bonding Using Interposer Pads

Shm H

Amendment under 37 CFR 1.116

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

4-28-03

Michael K. Skrehot

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 02/26/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Please amend the specification as follows:

In the Claims:

Please cancel Claim 22.

RECEIVED
MAY - 6 2003
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